

General Description

The Sanrise SRC65R230B is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC65R230B break down voltage is 650V and it has a high rugged avalanche characteristics. The SRC65R230B is available in PDFN8*8-4 package.

Features

- Ultra Low $R_{DS(ON)} = 230m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 38.4nC$ typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- Non-automotive Qualified

Application

- UPS, Inverter, etc
- Solar
- High Power AC/DC Power Supply

Symbol

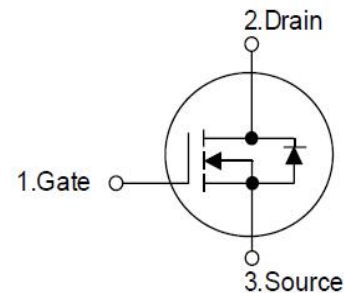
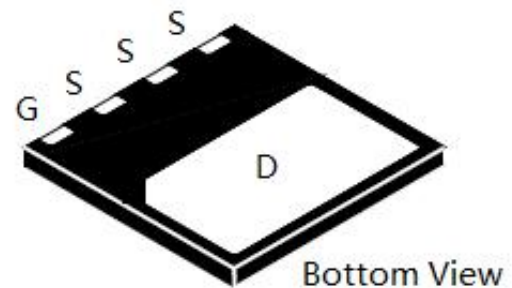


Figure 1 Symbol of SRC65R230B

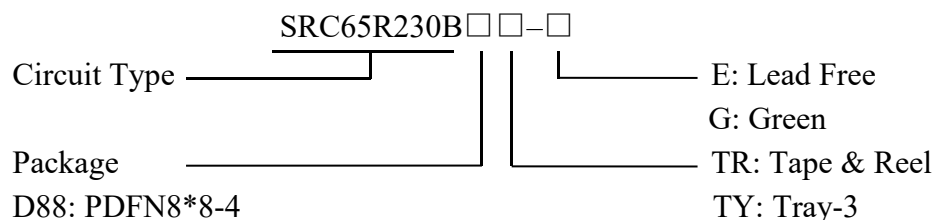
Package Type



PDFN8*8-4

Figure 2 Package Type of SRC65R230B

Ordering Information



Package	Part Number	Marking ID	Packing Type
	Green	Green	
PDFN8*8-4	SRC65R230BD88TR-G	SRC65R230BD88G	Tape & Reel

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±30	V
Continuous Drain Current	$T_C=25^{\circ}C$	I_D	21.2	A
	$T_C=125^{\circ}C$		9.5	
Pulsed Drain Current (Note 2)		I_{DM}	64	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	200	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.7	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	2.5	A
Continuous Diode Forward Current		I_S	21.2	A
Diode Pulse Current		$I_{S,PULSE}$	64	A
Operating Junction Temperature		T_J	150	°C
Storage Temperature		T_{STG}	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $I_{AS}=2.5A$, $V_{DD}=60V$, $R_G=25\Omega$, Starting $T_J=25^{\circ}C$

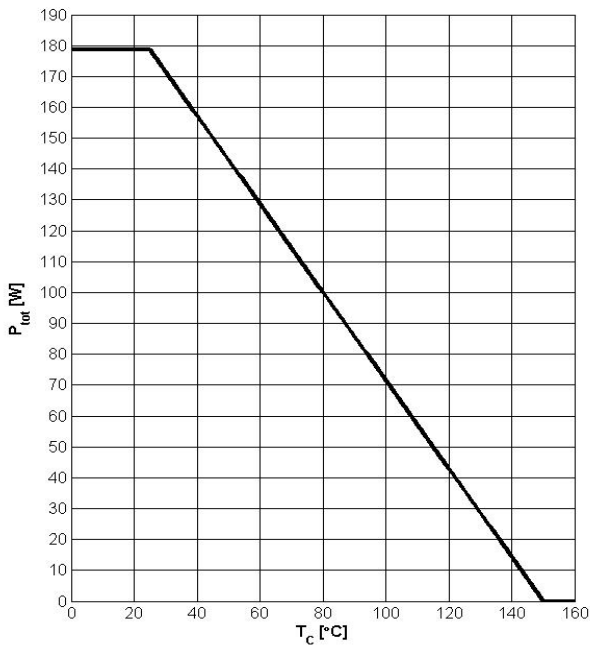
Electrical Characteristics

$T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified.

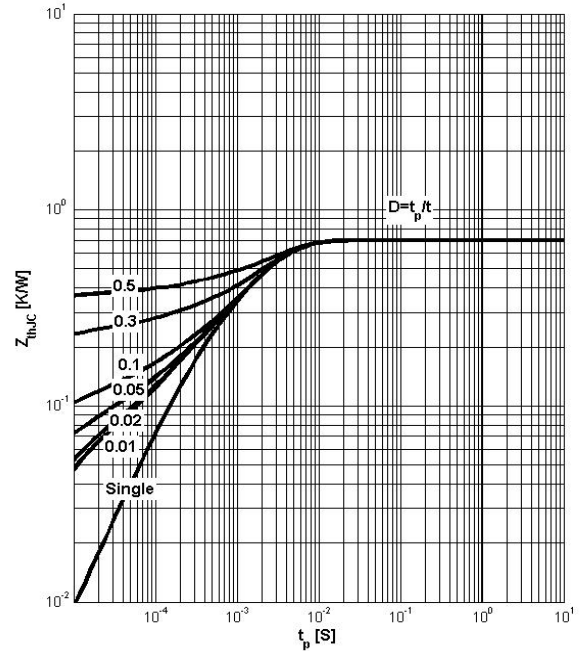
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	650			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=650V, V_{GS}=0V$			10	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=30V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-30V, V_{DS}=0V$			-1.0	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.3	3.3	4.3	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=10.0A$		187	230	mΩ
Gate Resistance	R_G	f=1MHz, Open Drain		1.7		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		1660		pF
Output Capacitance	C_{OSS}			1820		
Reverse Transfer Capacitance	C_{RSS}			23		
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 480V$		71		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			301		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=10.0A, R_G=3.4\Omega, V_{GS}=10V$		11		ns
Rise Time	t_r			10		
Turn-off Delay Time	$t_{d(off)}$			76		
Fall Time	t_f			8		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=480V, I_D=10.0A, V_{GS}=0\text{ to }10V$		10.8		nC
Gate to Drain Charge	Q_{gd}			12.3		
Gate Charge Total	Q_g			38.4		
Gate Plateau Voltage	$V_{plateau}$			5.4		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=10.0A$		0.87	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=400V, I_F=10.0A, dI_F/dt=100.0A/\mu s$		122		ns
Reverse Recovery Charge	Q_{rr}			0.57		μC
Peak Reverse Recovery Current	I_{rrm}			9.4		A

Note:

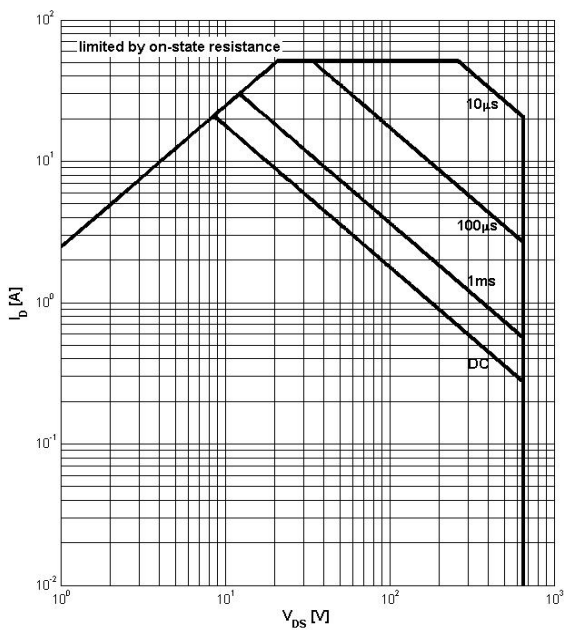
- $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V
- $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480V

Typical Performance Characteristics
Figure 3: Power Dissipation


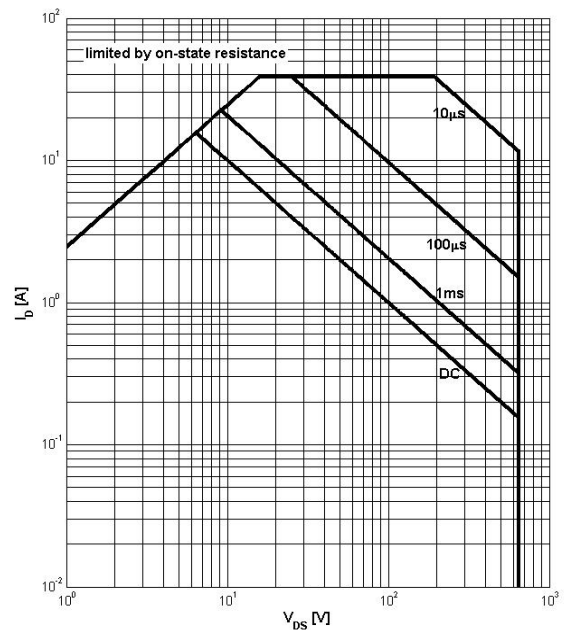
$$P_{tot} = f(T_c)$$

Figure 4: Max. Transient Thermal Impedance


$$Z_{(thJC)} = f(t_p); \text{ parameter: } D = t_p/T$$

Figure 5: Safe Operating Area


$$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

Figure 6: Safe Operating Area


$$I_D = f(V_{DS}); T_c = 80^\circ\text{C}; V_{GS} > 7\text{V}; \text{ parameter } t_p$$

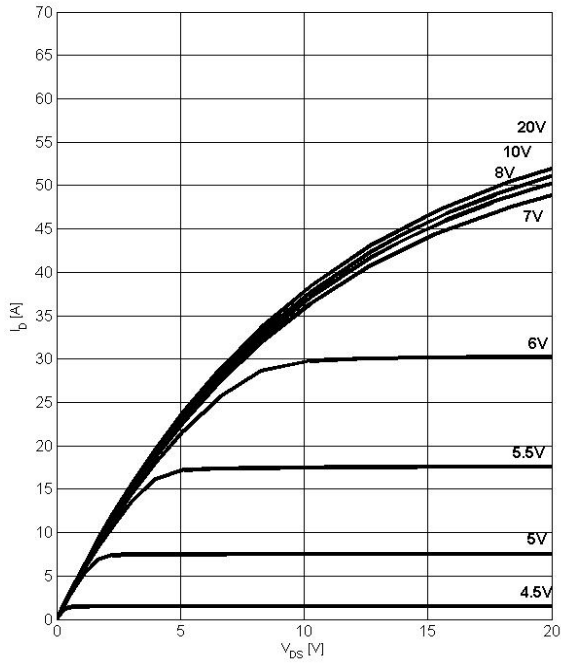
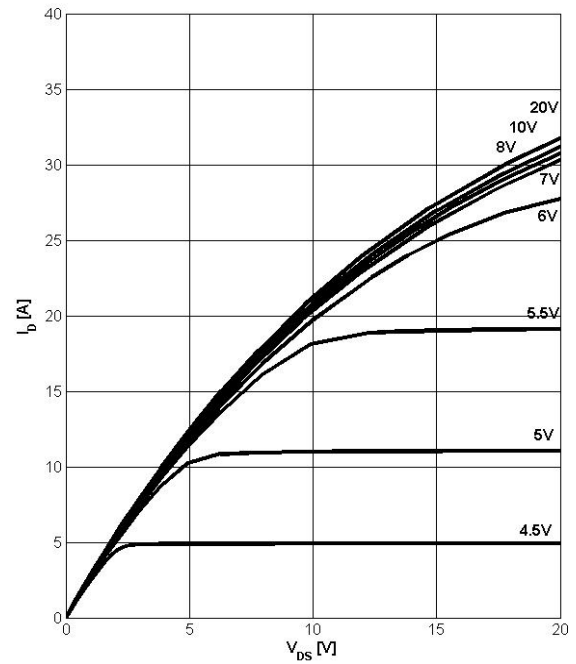
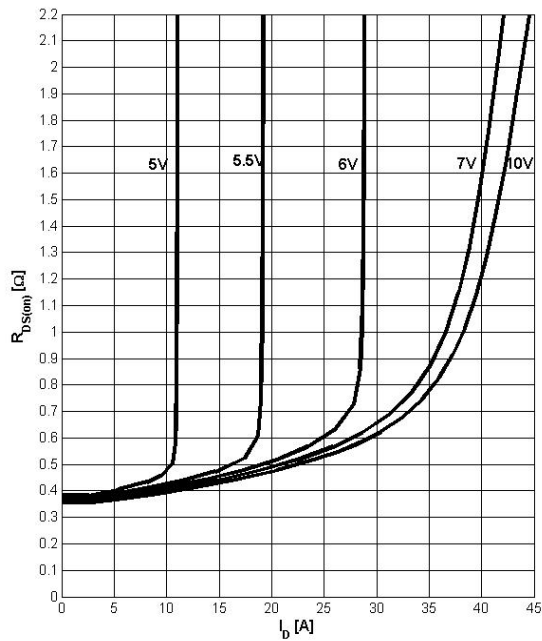
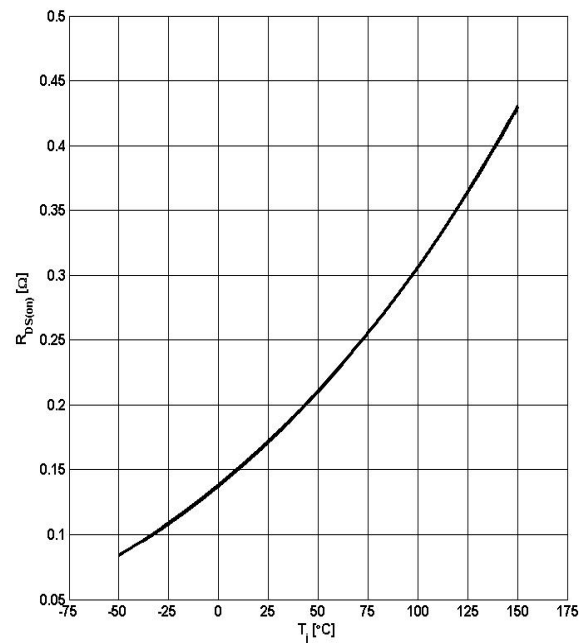
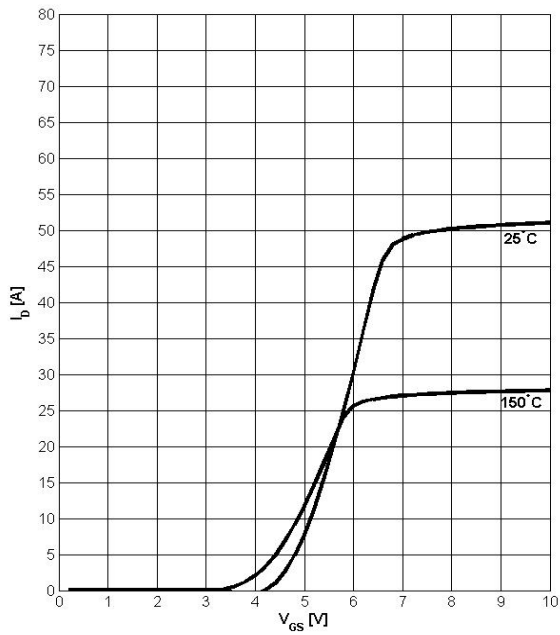
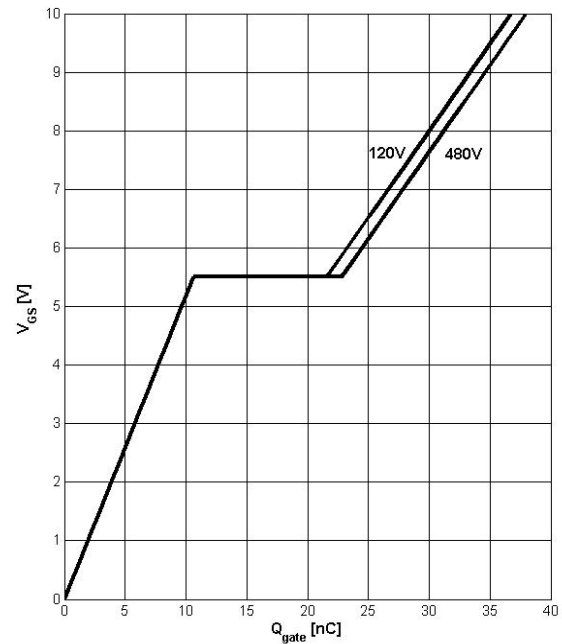
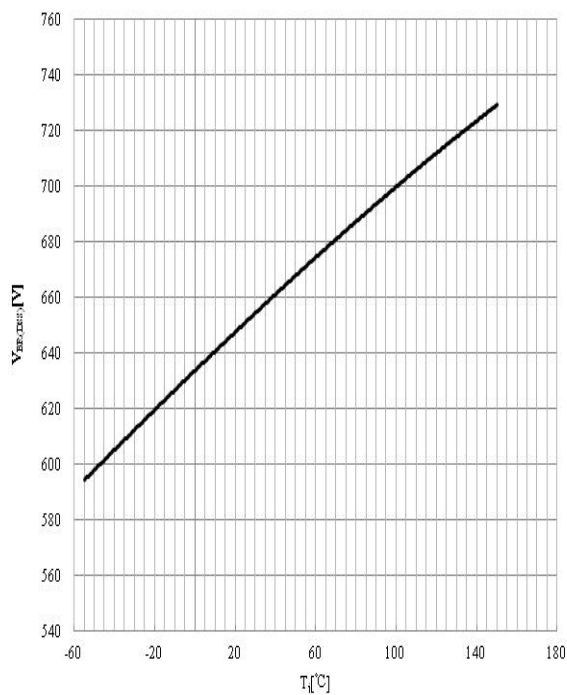
Figure 7: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 8: Typ. Output Characteristics

 $I_D = f(V_{DS}); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 9: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(I_D); T_j = 125^\circ\text{C}; \text{parameter: } V_{GS}$
Figure 10: Typ. Drain-Source On-State Resistance

 $R_{DS(ON)} = f(T_j); I_D = 10\text{A}; V_{GS} = 10\text{V}$

Figure 11: Typ. Transfer Characteristics


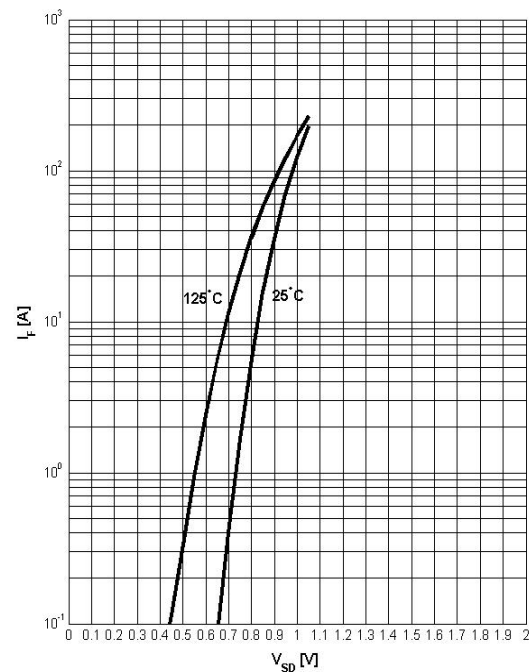
$$I_D = f(V_{GS}); V_{DS} = 20V$$

Figure 12: Typ. Gate Charge


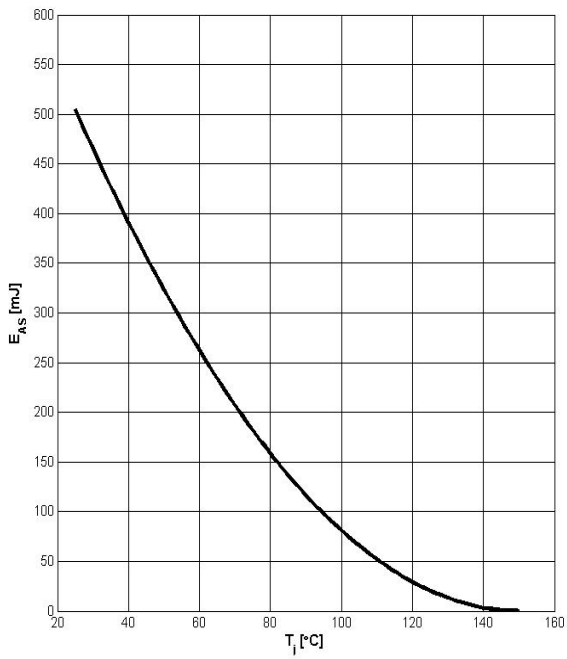
$$V_{GS} = f(Q_{gate}), I_D = 10A \text{ pulsed}$$

Figure 13: Drain-Source Breakdown Voltage


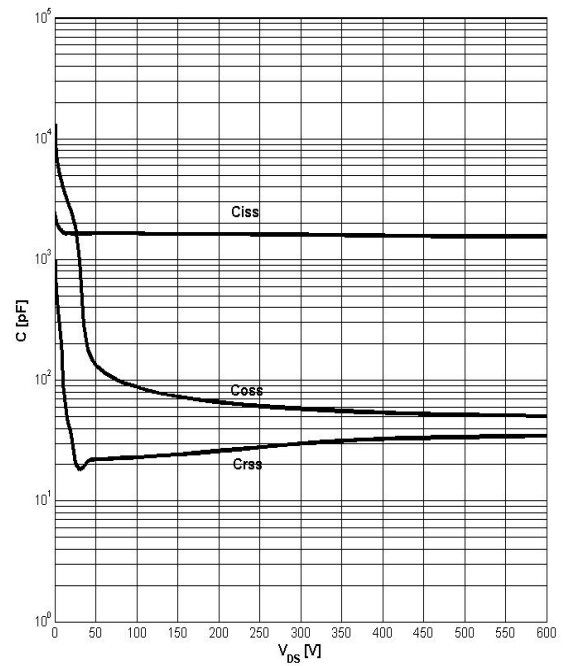
$$V_{BR(DSS)} = f(T_j); I_D = 10mA$$

Figure 14: Forward Characteristics of Reverse Diode


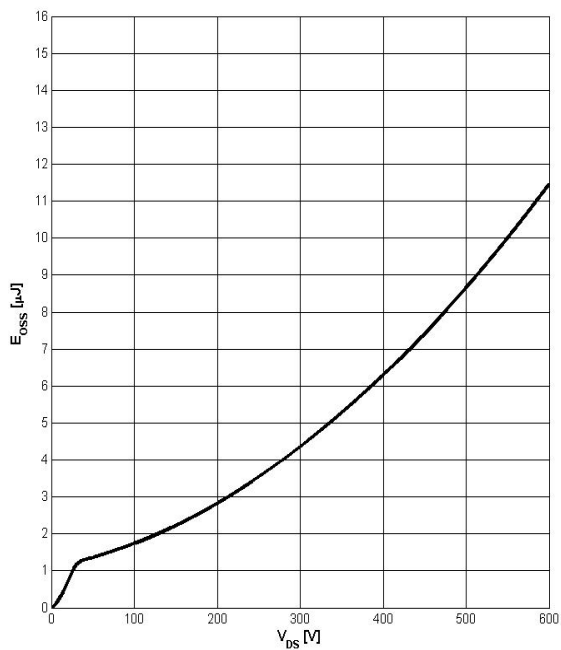
$$I_F = f(V_{SD}); \text{parameter: } T_j$$

Figure 15: Avalanche Energy


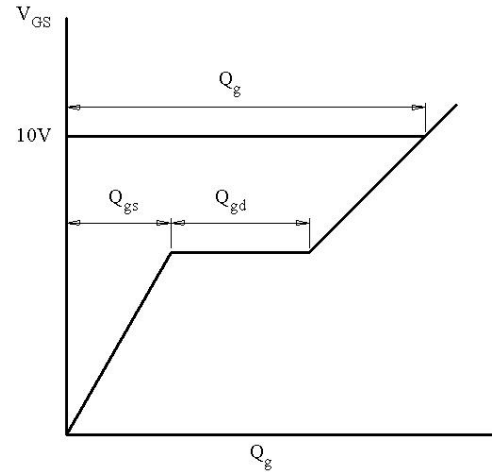
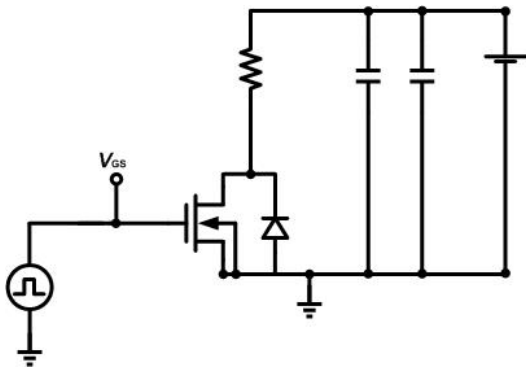
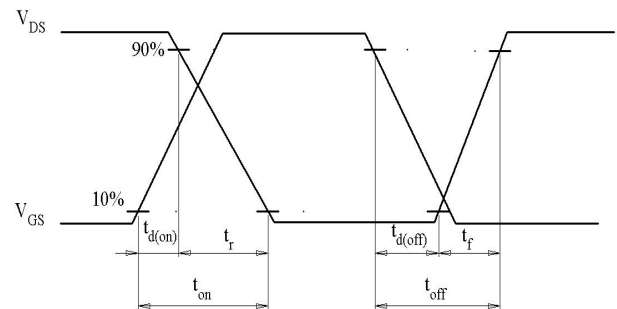
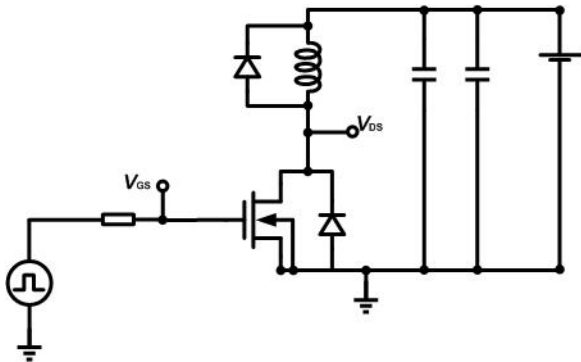
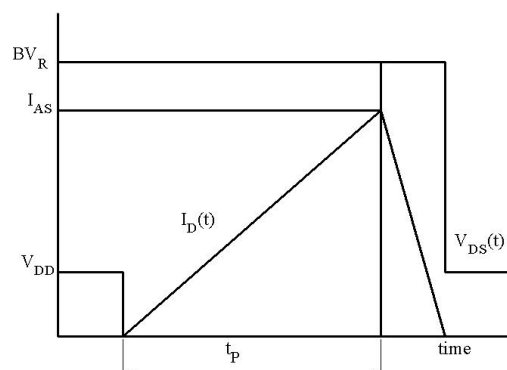
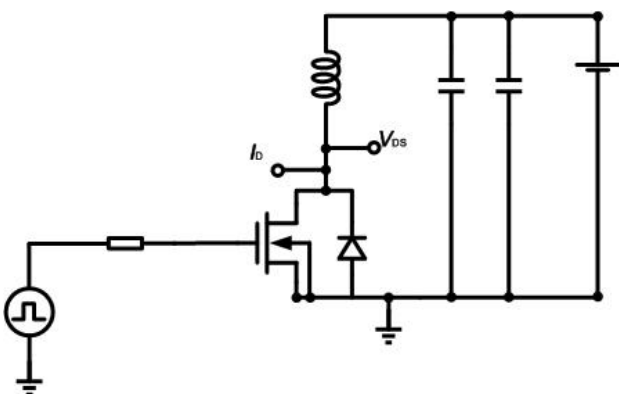
$$E_{AS}=f(T_j); I_D=3.6A; V_{DD}=60V$$

Figure 16: Typ. Capacitances


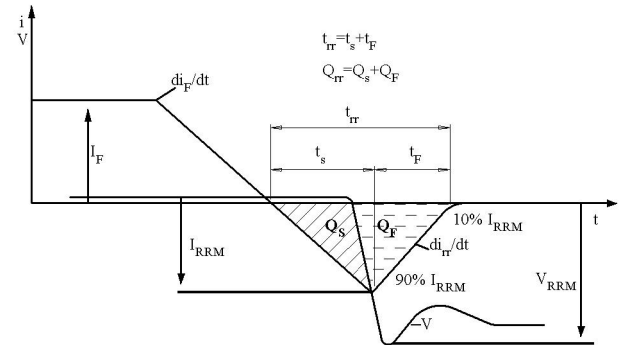
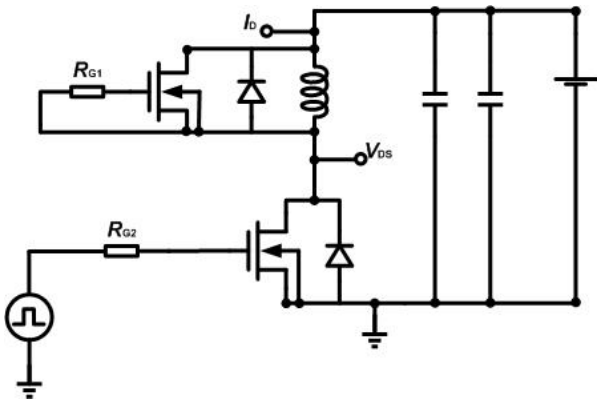
$$C=f(V_{DS}); V_{GS}=0; f=1MHz$$

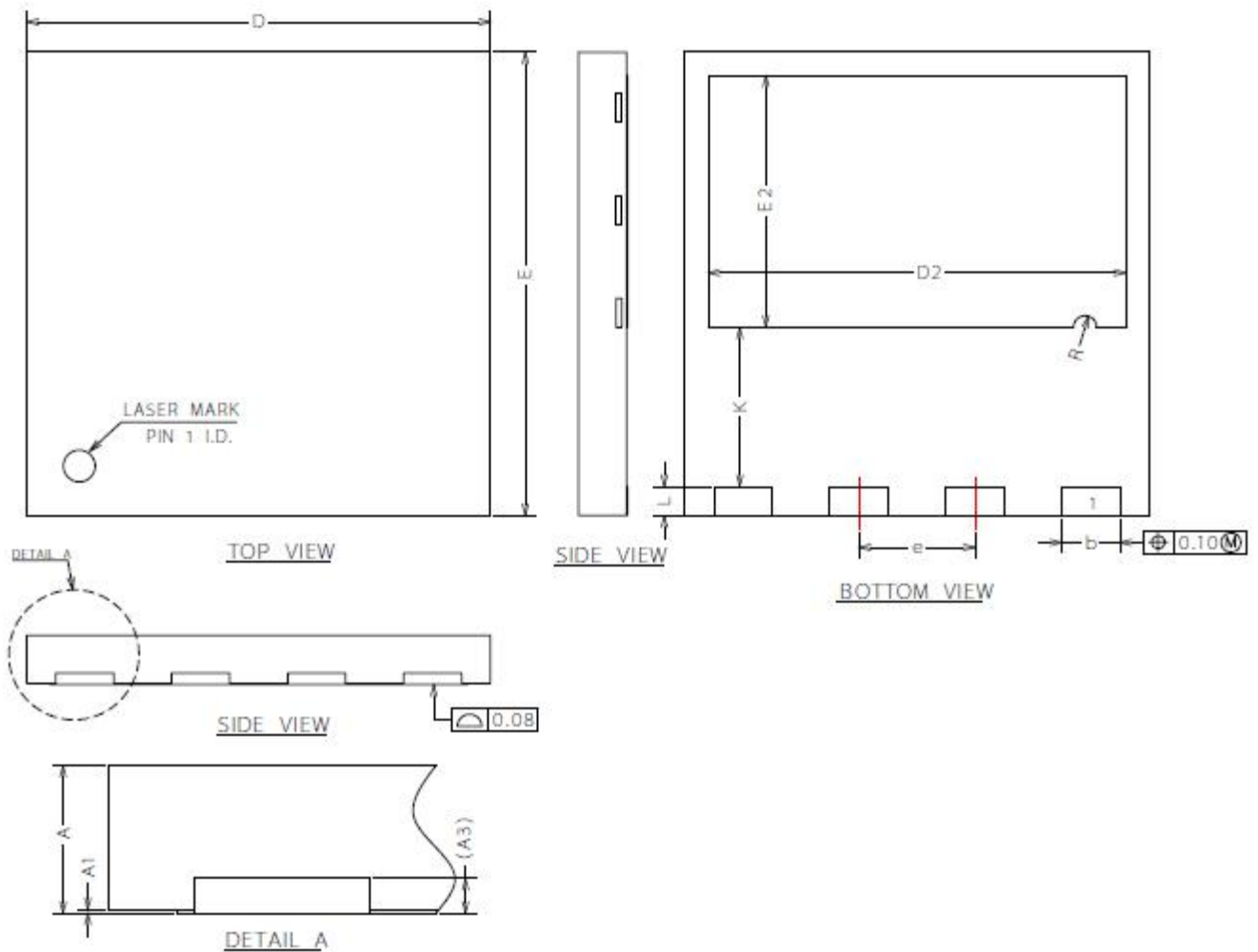
Figure 17: C_{oss} Stored Energy


$$E_{oss}=f(V_{DS})$$

Test Circuits
1. Gate Charge Test Circuit & Waveform

2. Switch Time Test Circuit

3. Unclaimed Inductive Switching Test Circuit & Waveforms


4. Test Circuit and Waveform for Diode Characteristics



Mechanical Dimensions
PDFN8*8-4
Unit: mm


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3	0.20REF		
b	0.90	1.00	1.10
D	7.90	8.00	8.10
D2	7.10	7.20	7.30
E	7.90	8.00	8.10
E2	4.25	4.35	4.45
e	2.00(BSC)		
K	2.65	2.75	2.85
L	0.40	0.50	0.60
R	0.20REF		



Shenzhen Sanrise Technology Co., LTD

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